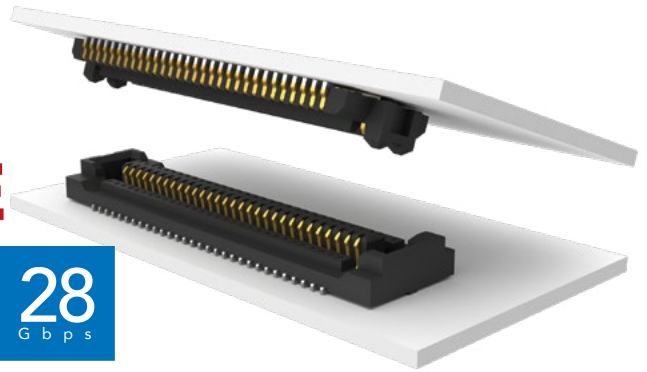


# ULTRA-LOW PROFILE HEADER & SOCKET

(0.50 mm) .0197" PITCH • SLH/TLH SERIES



**SLH**  
Mates:  
TLH

**TLH**  
Mates:  
SLH

## SPECIFICATIONS

**Insulator Material:**  
Black Liquid Crystal Polymer  
**Contact Material:**  
Copper Alloy  
**Plating:**  
Au over 50 μ" (1.27 μm) Ni  
**Current Rating:**  
2.1 A per pin  
(2 pins powered)  
**Operating Temp Range:**  
-55 °C to +125 °C

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max  
**Board Stacking:**  
For applications requiring two or more connectors per board, contact [ipg@samtec.com](mailto:ipg@samtec.com)

SLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION	"X"R
-----	------------------	------------	----------------	---	--------	--------	------

-010,  
-020,  
-030  
(Per Row)

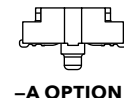
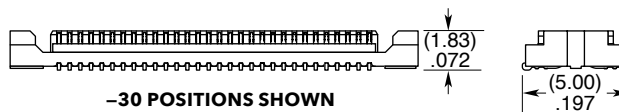
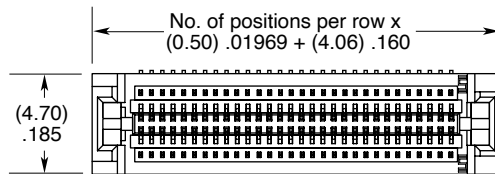
-1.50  
=1.50 mm

-G  
= 10 μ"  
(0.25 μm)  
Gold in  
contact,  
Gold flash  
on tail

-A  
= Alignment  
Pin

-K  
= (3.00 mm)  
.118" DIA  
Polyimide  
Film  
Pick &  
Place Pad

(Leave blank  
for tape &  
reel)  
  
-FR  
= Full Reel  
Tape & Reel  
(must order  
max. quantity  
per reel;  
contact  
Samtec for  
quantity  
breaks)



## MATED HEIGHT\*

SLH LEAD STYLE	TLH LEAD STYLE
-1.50	-0.50 (2.00) .0787

\*Processing conditions will affect mated height.

TLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION	"X"R
-----	------------------	------------	----------------	---	--------	--------	------

-010,  
-020,  
-030  
(Per Row)

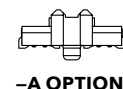
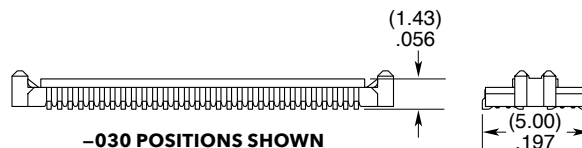
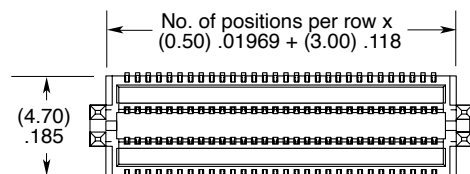
-0.50  
=0.50 mm

-G  
= 10 μ"  
(0.25 μm)  
Gold in  
contact,  
Gold flash  
on tail

-A  
= Alignment  
Pin

-K  
= (3.00 mm)  
.118" DIA  
Polyimide  
Film  
Pick &  
Place Pad

(Leave blank  
for tape &  
reel)  
  
-FR  
= Full Reel  
Tape & Reel  
(must order  
max. quantity  
per reel;  
contact  
Samtec for  
quantity  
breaks)



**Note:**  
Some lengths, styles and options are non-standard, non-returnable.